- **Member of the Texas Instruments Widebus+™ Family**
- **Operates From 1.65 V to 3.6 V**
- **Inputs Accept Voltages to 5.5 V**
- **Max t_{pd} of 4.1 ns at 3.3 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2 V at V_{CC} = 3.3 V, T_A = 25°C**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

description/ordering information

This 32-bit buffer/driver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVCH32244A is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device can be used as eight 4-bit buffers, four 8-bit buffers, two 16-bit buffers, or one 32-bit buffer. It provides true outputs and symmetrical active-low output-enable ($\overline{OE}$) inputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

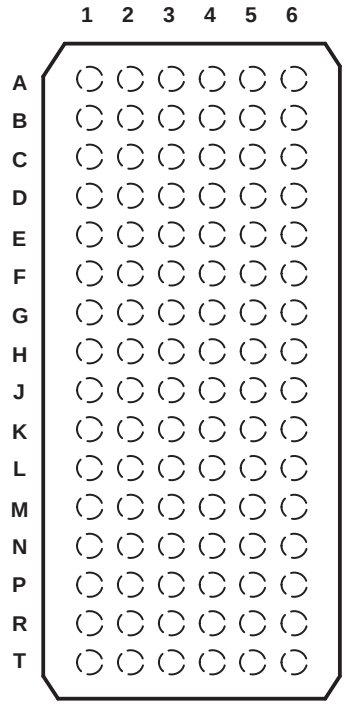
Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	LFBGA − GKE	Tape and reel	SN74LVCH32244AGKER	CH244A
	LFBGA − ZKE (Pb-free)		SN74LVCH32244AZKER	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

GKE OR ZKE PACKAGE
(TOP VIEW)



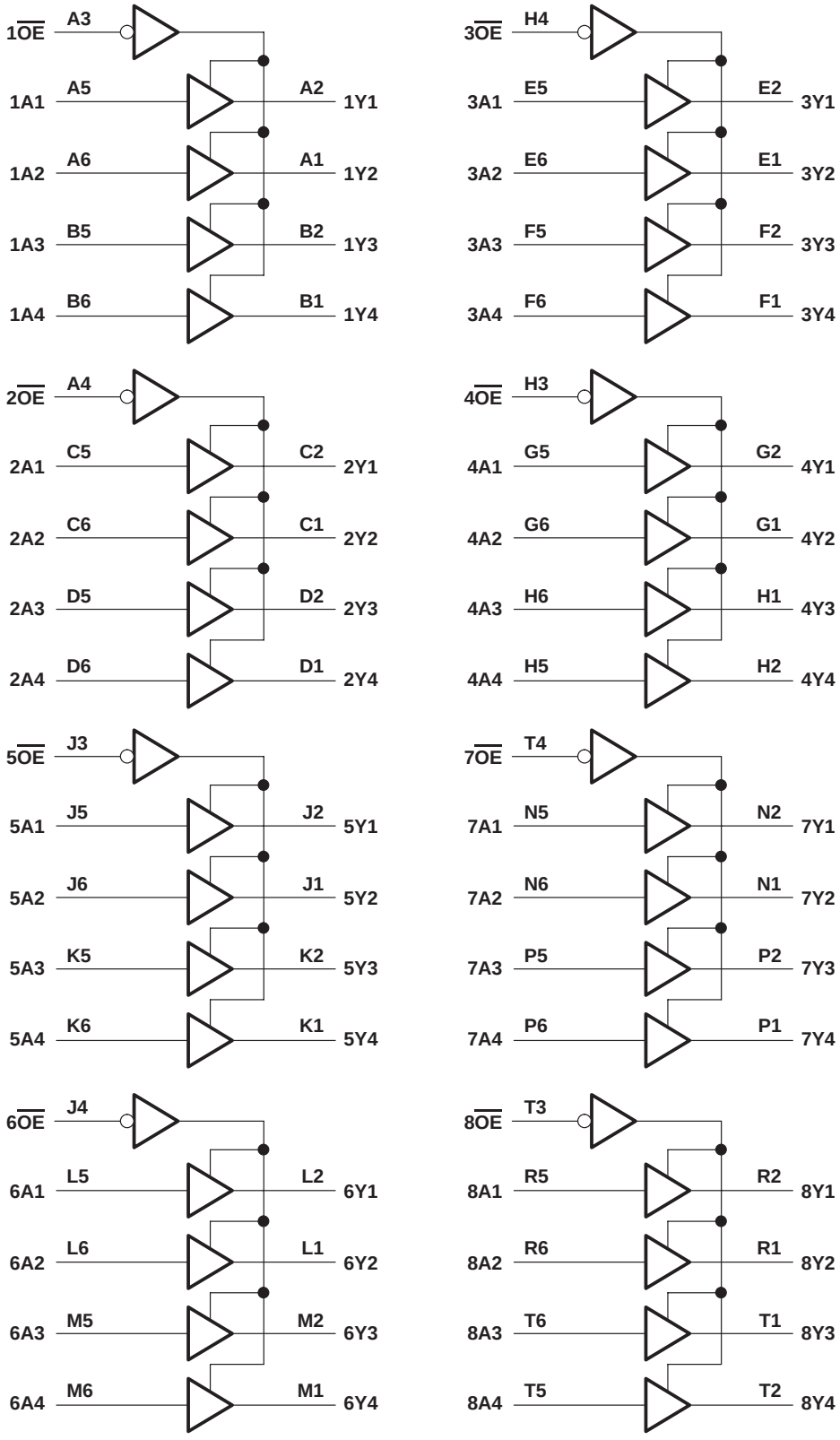
terminal assignments

	1	2	3	4	5	6
A	1Y2	1Y1	$1\overline{OE}$	$2\overline{OE}$	1A1	1A2
B	1Y4	1Y3	GND	GND	1A3	1A4
C	2Y2	2Y1	V_{CC}	V_{CC}	2A1	2A2
D	2Y4	2Y3	GND	GND	2A3	2A4
E	3Y2	3Y1	GND	GND	3A1	3A2
F	3Y4	3Y3	V_{CC}	V_{CC}	3A3	3A4
G	4Y2	4Y1	GND	GND	4A1	4A2
H	4Y3	4Y4	$4\overline{OE}$	$3\overline{OE}$	4A4	4A3
J	5Y2	5Y1	$5\overline{OE}$	$6\overline{OE}$	5A1	5A2
K	5Y4	5Y3	GND	GND	5A3	5A4
L	6Y2	6Y1	V_{CC}	V_{CC}	6A1	6A2
M	6Y4	6Y3	GND	GND	6A3	6A4
N	7Y2	7Y1	GND	GND	7A1	7A2
P	7Y4	7Y3	V_{CC}	V_{CC}	7A3	7A4
R	8Y2	8Y1	GND	GND	8A1	8A2
T	8Y3	8Y4	$8\overline{OE}$	$7\overline{OE}$	8A4	8A3

FUNCTION TABLE
(each 4-bit buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 6.5 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1) . . . . . −0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, V_O (see Notes 1 and 2) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0) . . . . . −50 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . −50 mA
Continuous output current, I_O . . . . . ±50 mA
Continuous current through each V_{CC} or GND . . . . . ±100 mA
Package thermal impedance, θ_{JA} (see Note 3): GKE/ZKE . . . . . 40°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The value of V_{CC} is provided in the recommended operating conditions table.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V_{CC}	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
V_{IH}	High-level input voltage	V_{CC} = 1.65 V to 1.95 V	0.65 × V_{CC}		V
		V_{CC} = 2.3 V to 2.7 V	1.7		
		V_{CC} = 2.7 V to 3.6 V	2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65 V to 1.95 V		0.35 × V_{CC}	V
		V_{CC} = 2.3 V to 2.7 V		0.7	
		V_{CC} = 2.7 V to 3.6 V		0.8	
V_I	Input voltage		0	5.5	V
V_O	Output voltage	High or low state	0	V_{CC}	V
		3-state	0	5.5	
I_{OH}	High-level output current	V_{CC} = 1.65 V		−4	mA
		V_{CC} = 2.3 V		−8	
		V_{CC} = 2.7 V		−12	
		V_{CC} = 3 V		−24	
I_{OL}	Low-level output current	V_{CC} = 1.65 V		4	mA
		V_{CC} = 2.3 V		8	
		V_{CC} = 2.7 V		12	
		V_{CC} = 3 V		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature		−40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	MIN	TYP†	MAX	UNIT
V_{OH}	I_{OH} = −100 μA		1.65 V to 3.6 V	V_{CC}−0.2			V
	I_{OH} = −4 mA		1.65 V	1.2			
	I_{OH} = −8 mA		2.3 V	1.7			
	I_{OH} = −12 mA		2.7 V	2.2			
			3 V	2.4			
	I_{OH} = −24 mA		3 V	2.2			
V_{OL}	I_{OL} = 100 μA		1.65 V to 3.6 V			0.2	V
	I_{OL} = 4 mA		1.65 V			0.45	
	I_{OL} = 8 mA		2.3 V			0.7	
	I_{OL} = 12 mA		2.7 V			0.4	
	I_{OL} = 24 mA		3 V			0.55	
I_I	V_I = 0 to 5.5 V		3.6 V			±5	μA
$I_{I(hold)}$	V_I = 0.58 V		1.65 V	25			μA
	V_I = 1.07 V			−25			
	V_I = 0.7 V		2.3 V	45			
	V_I = 1.7 V			−45			
	V_I = 0.8 V		3 V	75			
	V_I = 2 V			−75			
	V_I = 0 to 3.6 V‡		3.6 V			±500	
I_{off}	V_I or V_O = 5.5 V		0			±10	μA
I_{OZ}	V_O = 0 to 5.5 V		3.6 V			±10	μA
I_{CC}	V_I = V_{CC} or GND	I_O = 0	3.6 V			40	μA
	3.6 V ≤ V_I ≤ 5.5 V§					40	
ΔI_{CC}	One input at V_{CC} − 0.6 V,	Other inputs at V_{CC} or GND	2.7 V to 3.6 V			500	μA
C_i	V_I = V_{CC} or GND		3.3 V		5.5		pF
C_o	V_O = V_{CC} or GND		3.3 V		6		pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.
§ This applies in the disabled state only.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 1.8 V ± 0.15 V		V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	¶	¶	¶	¶		4.7	1.1	4.1	ns
t_{en}	$\overline{OE}$	Y	¶	¶	¶	¶		5.8	1	4.6	ns
t_{dis}	$\overline{OE}$	Y	¶	¶	¶	¶		6.2	1.8	5.8	ns
$t_{sk(o)}$										1.5	ns

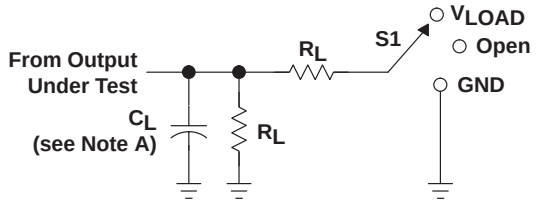
¶ This information was not available at the time of publication.

operating characteristics, $T_A = 25°C$

PARAMETER			TEST CONDITIONS	V_{CC} = 1.8 V	V_{CC} = 2.5 V	V_{CC} = 3.3 V	UNIT
				TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	f = 10 MHz	†	†	34	pF
		Outputs disabled		†	†	4	

† This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION

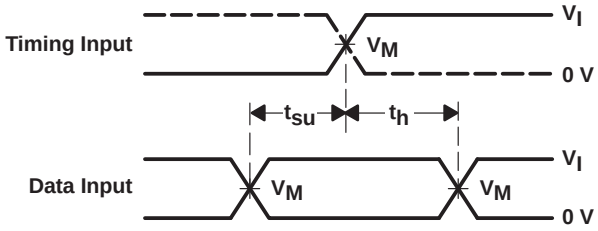


LOAD CIRCUIT

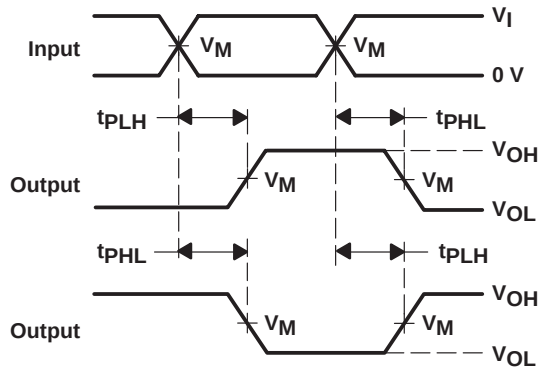
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V_{CC}	INPUTS		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
1.8 V ± 0.15 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 kΩ	0.15 V
2.5 V ± 0.2 V	V_{CC}	≤2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V ± 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V

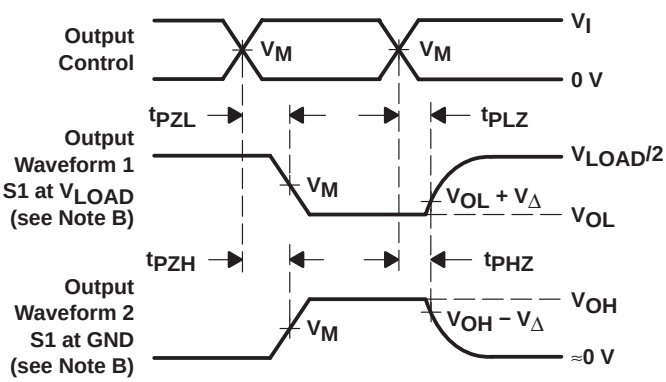
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

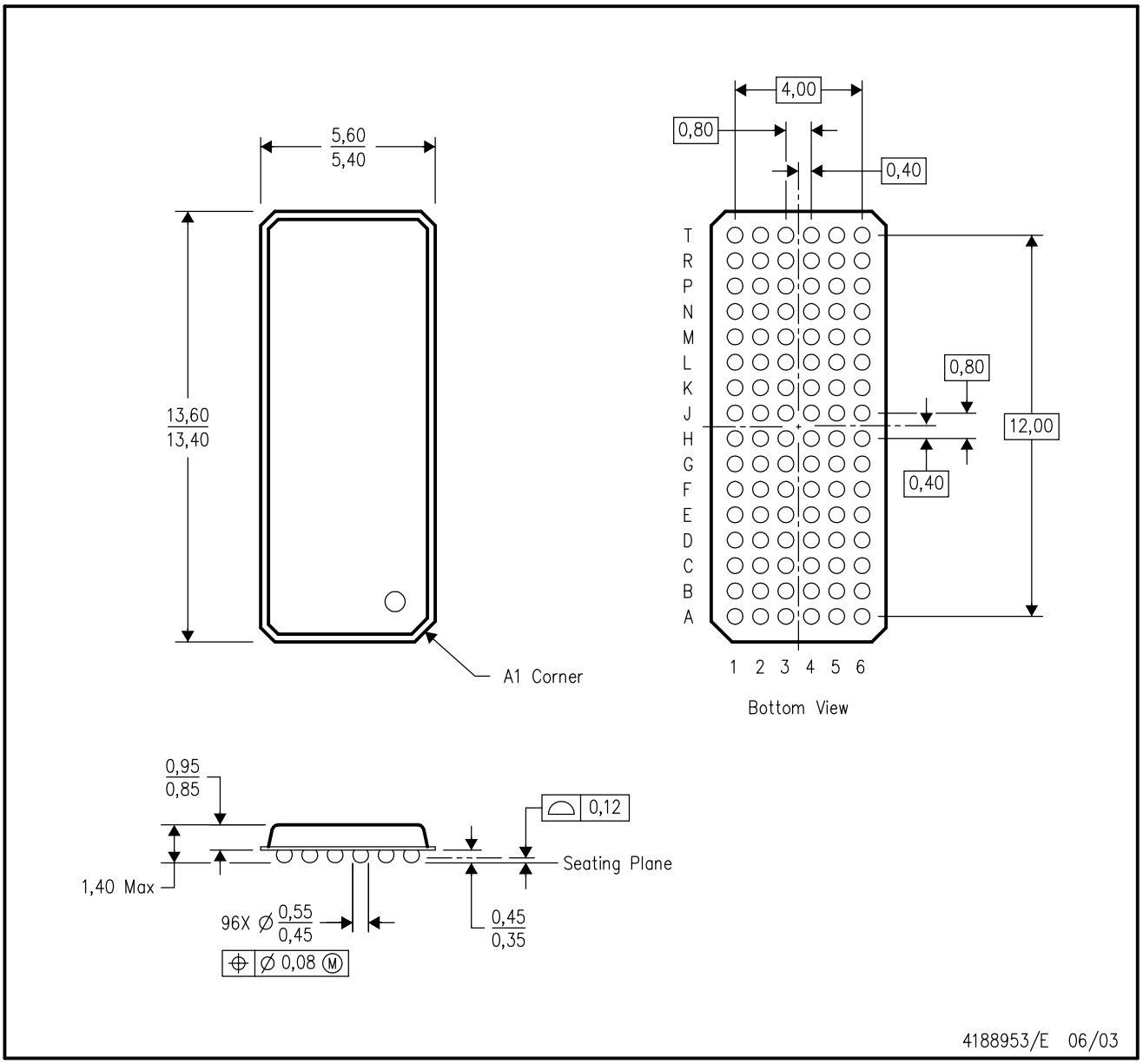


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω.
D. The outputs are measured one at a time with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

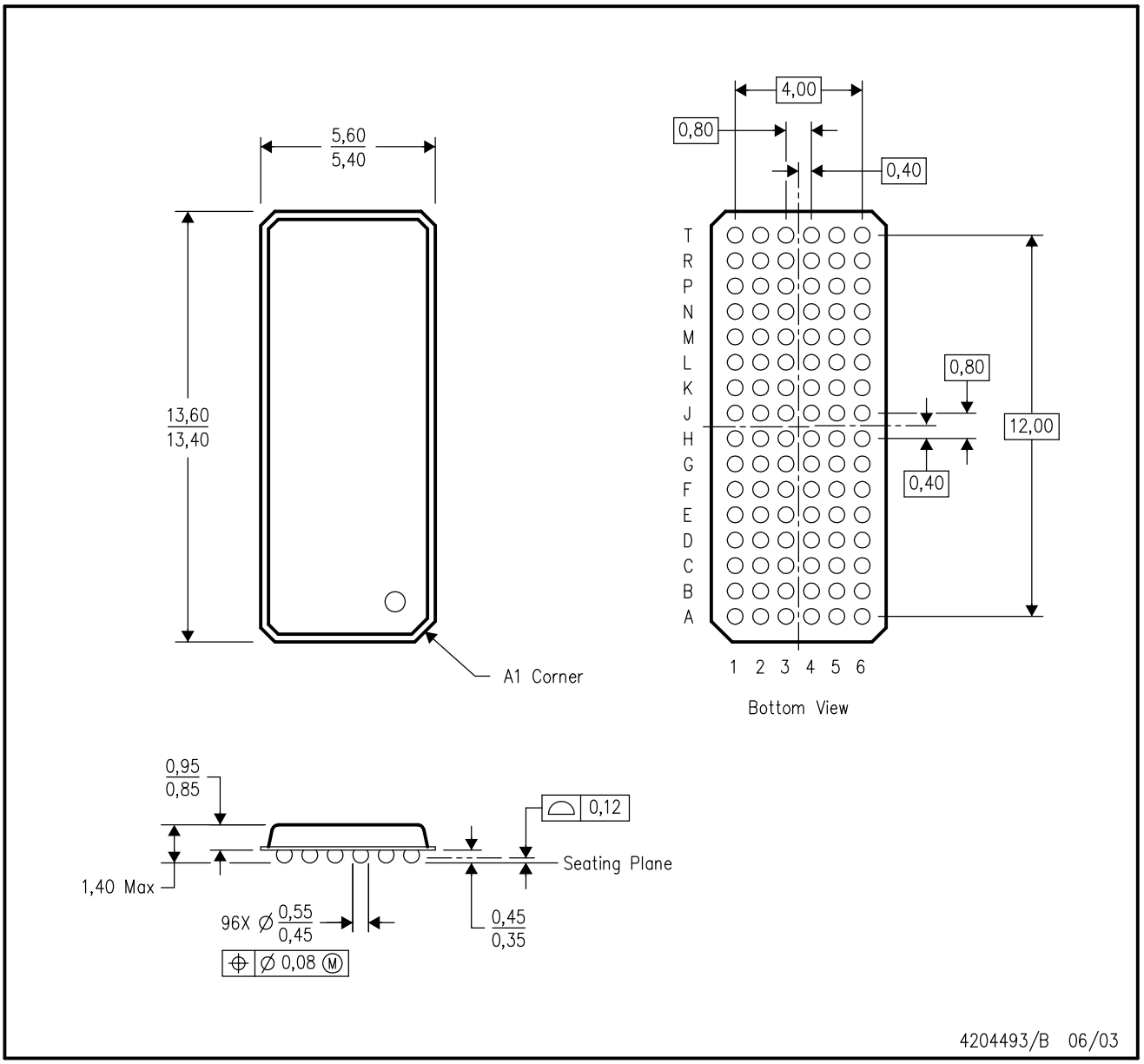
GKE (R–PBGA–N96) PLASTIC BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. MicroStar BGA™ configuration
D. Falls within JEDEC MO–205 variation CC.
E. This package is tin–lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead–free.

MicroStar BGA is a trademark of Texas Instruments.

ZKE (R–PBGA–N96) PLASTIC BALL GRID ARRAY



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. MicroStar BGA™ configuration
D. Falls within JEDEC MO–205 variation CC.
E. This package is lead–free. Refer to the 96 GKE package (drawing 4188953) for tin–lead (SnPb).

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